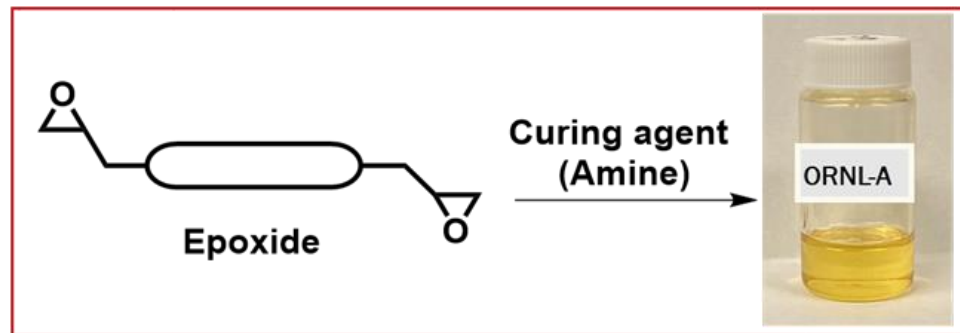
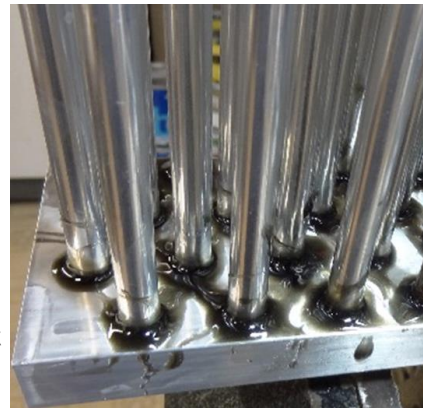
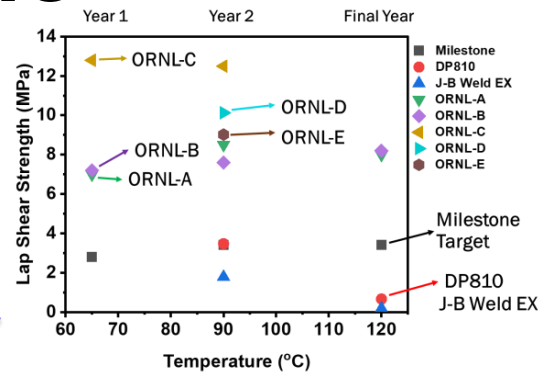
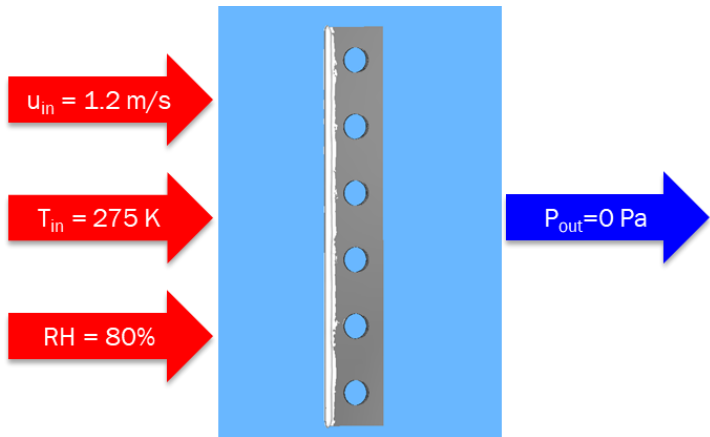
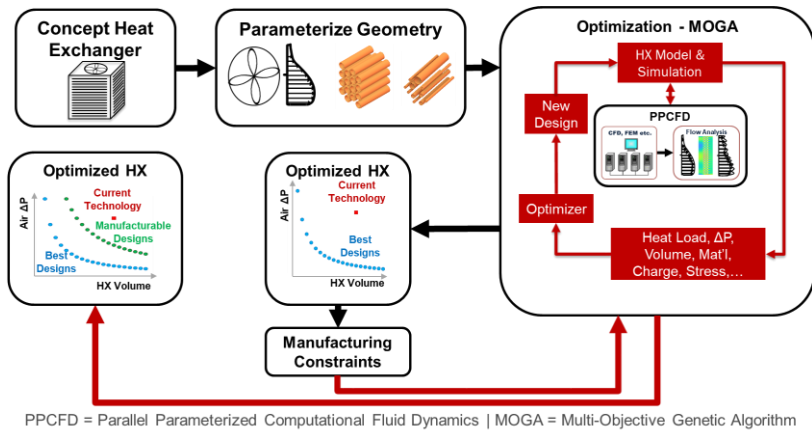


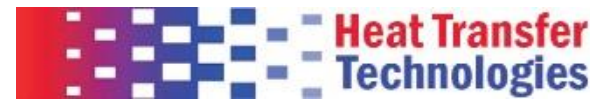
Hybrid Manufacturing for High Performance Air-to-Refrigerant Heat Exchangers



Performing Organizations: University of Maryland, Heat Transfer Technologies, LLC., Oak Ridge National Laboratory
 Prof. Reinhard Radermacher, Dr. Vikrant Aute
 vikrant@umd.edu
 DE-EE0009677



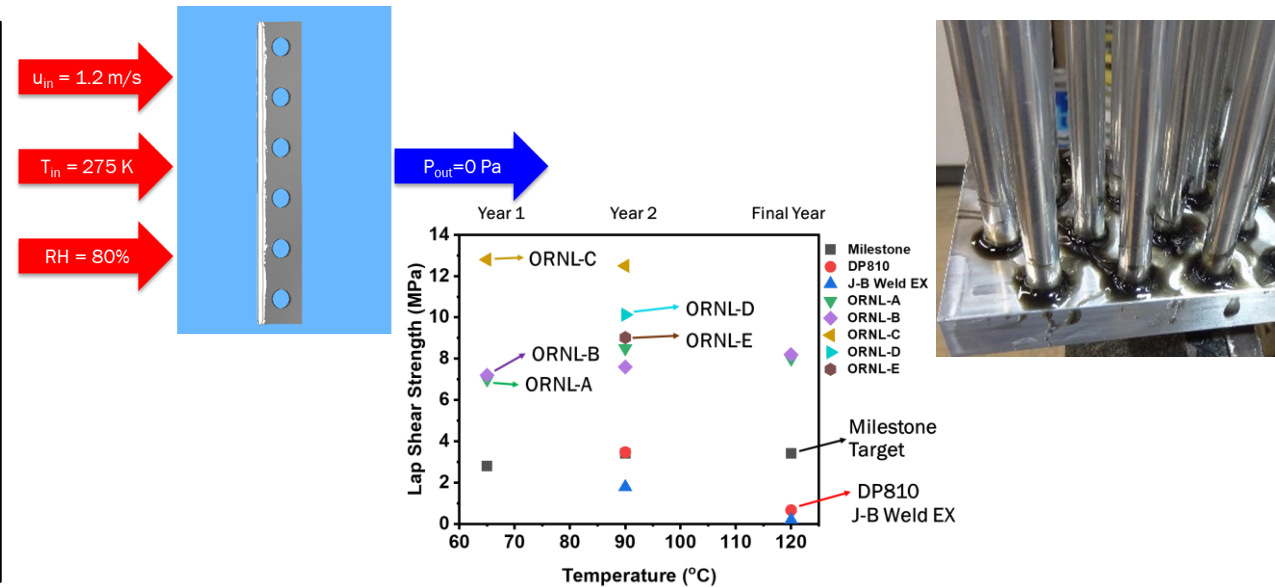
CENTER FOR ENVIRONMENTAL ENERGY ENGINEERING



Project Summary

Objective and outcome

- Develop adhesive-based hybrid manufacturing method for air-to-refrigerant HXs which is >50% cheaper & >36% less energy in manufacturing
- Develop novel air-to-refrigerant variable geometry HXs with higher compactness, improved frosting / maldistribution resilience, & less refrigerant
- Framework validation through laboratory-scale & field-scale experimental testing



Team and Partners



Stats

Performance Period: Oct. 2021 – Sept. 2024

DOE budget: \$1400K, Cost Share: \$350K

Milestone 1: 1st adhesive; HX design framework + proof-of-concept prototypes

Milestone 2: 2nd adhesive; Lab-scale HXs + testing

Milestone 3: Final adhesive; Field-scale HXs + testing

Problem

- **Heat eXchangers (HX) are key components in HVAC&R systems**
 - Hold refrigerant charge; impact system efficiency
- **Improved HXs can lead to**
 - Less refrigerant charge
 - Less material use, size/weight reduction
 - Lower energy consumption, emissions, & costs
- **Challenges in bringing new HX technology to market**
 - Novel designs must be at least 20% better
 - Lack of basic heat transfer & flow fundamentals, correlations
 - Component availability
 - Joining/manufacturing techniques
 - Flow maldistribution
 - Frost accumulation

Alignment

- **Develop an adhesive based hybrid manufacturing method for air-to-refrigerant HXs**
 - $\geq 50\%$ cheaper
 - $\geq 36\%$ less energy in manufacturing
 - More reliable than existing solder-based methods
- **Develop novel air-to-refrigerant variable geometry heat exchangers (VGHX)**
 - Contain less refrigerant
 - Are more compact
 - Are more resilient to frost growth & refrigerant maldistribution
- **Conduct frost accumulation & reliability tests**
 - Reduce refrigerant maldistribution from frost growth
- **Delivery of HX prototypes to industrial partners for independent performance testing**

Impact & Target Market

- **Impact**

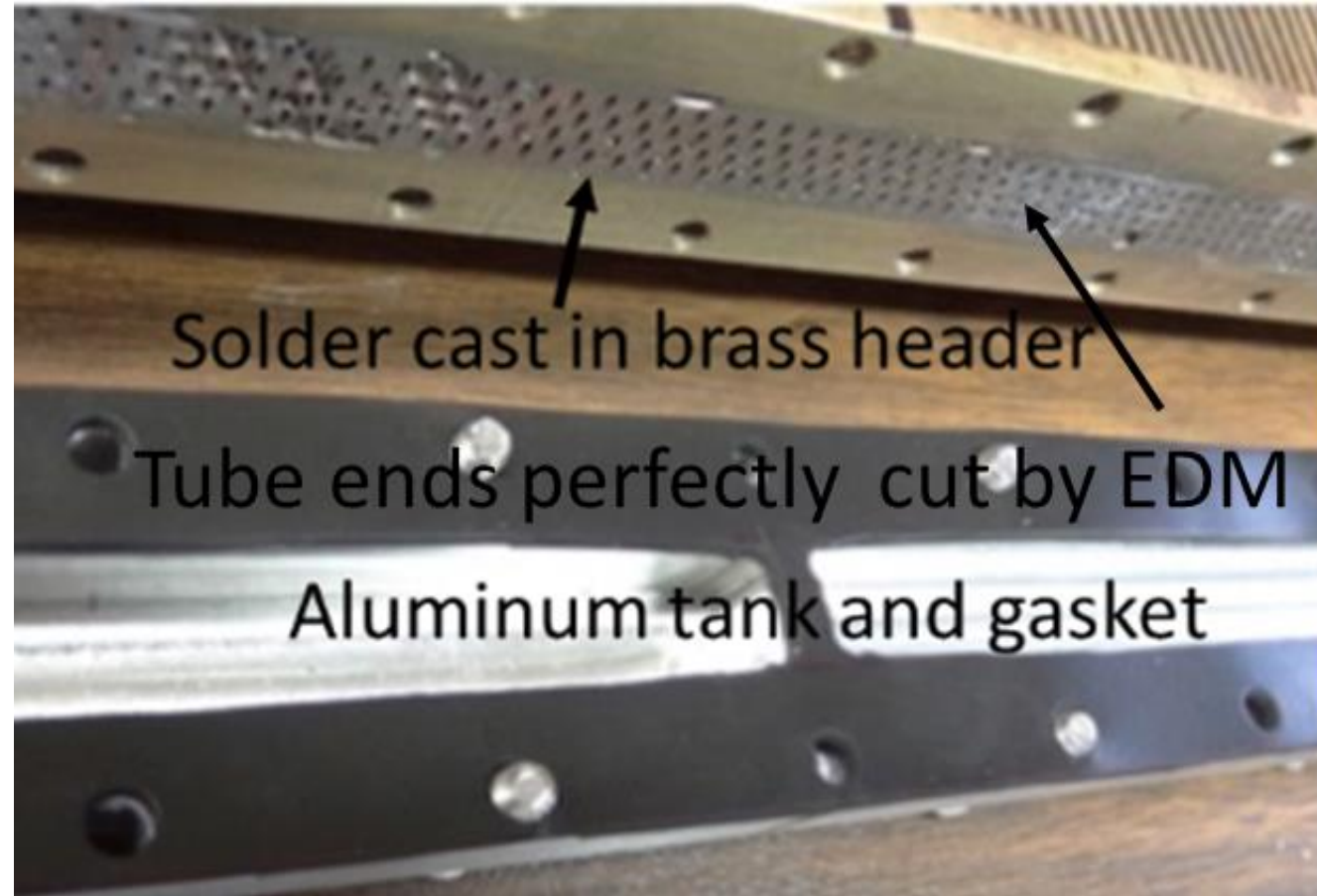
- New manufacturing method expected to be 50% cheaper & consume 36% less energy than existing solder-based methods
 - Adhesive-based approach has potential to reduce production barriers for next generation HXs
 - Improved reliability over solder-based methods to reduce refrigerant leakage (1.5-2.0% of total emissions)
- Novel HX designs with improved resilience to field challenges
 - $\geq 10\%$ longer operation time under frost accumulation conditions
 - $\geq 20\%$ improvement in uniformity of evaporator mass flow rate
- HX design framework and technical guidelines for adhesive-based hybrid manufacturing thereof
 - Modular technology with multiple product levels, e.g., fully variable geometry HXs (premium) vs. small-diameter round tubes with rectangular headers (affordable)
- Industry involvement in HX design development & testing with immediate and iterative feedback on commercial viability and tech-to-market

- **Target Market**

- Residential and commercial air conditioners and heat pumps
- New construction and retrofit applications

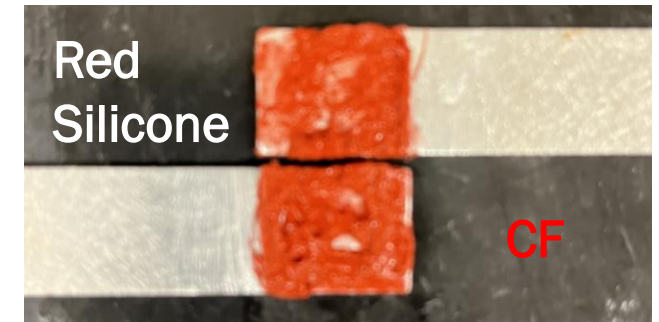
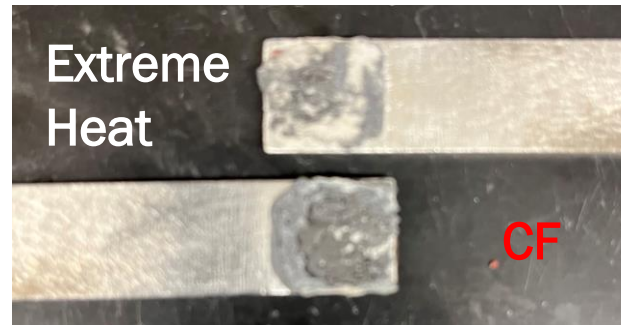
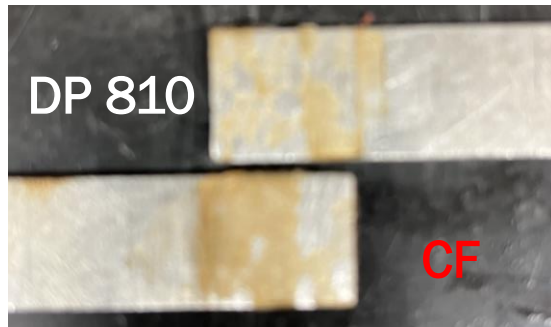
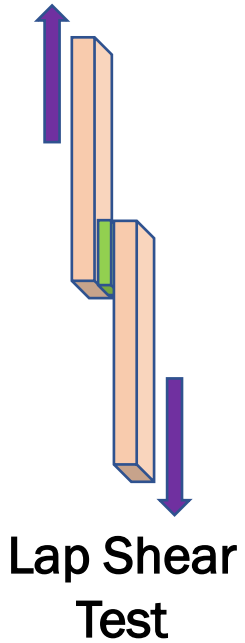
Approach: HX Manufacturing – State-of-the-Art

- **Cast based method**
 - High energy consumption to cast metals
 - Requires corrosive fluxes to clean metals
 - Costly EDM cutting of tube ends
 - Requires tanks and gasket seals



Approach: State-of-the-Art Commercial Adhesives

Commercial adhesives	Tested substrate	Temperature (°C)	Lap shear strength (MPa)
3M DP 810 (Acrylate)	Aluminum	90	3.47
J-B Weld Extreme Heat (Epoxy)	Aluminum	90	1.78
J-B Weld Hi-temp RTV (Silicone)	Aluminum	90	0.34



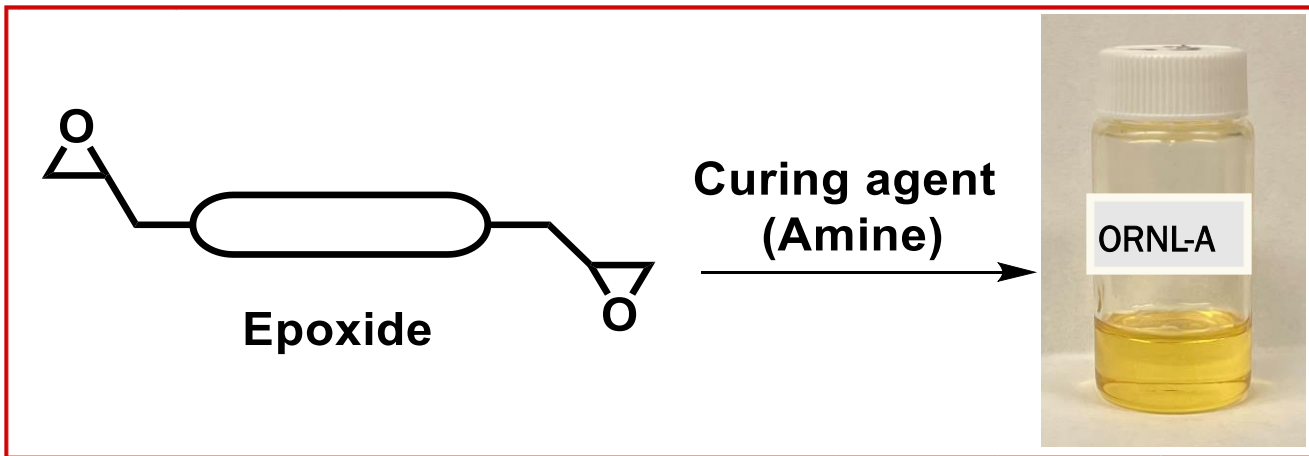
Cohesive Failure (CF): Failure occurs within adhesive which indicates weak adhesion

Approach: Initial Fabrication

- **Commercially available adhesives**
 - Previous work evaluated 23 options
 - Most had tube-adhesive leaks
 - Acrylic-Based DP810 → most promising
 - Withstood 2.8 MPa at room temperature (Max temperature 50°C)
 - Medium viscosity → hard penetration
- **Epoxy-based adhesives**
 - Excellent lap shear
 - Low viscosity → easy penetration
 - High-temp capable (>90°C)



Approach: Design of High Temperature Adhesives

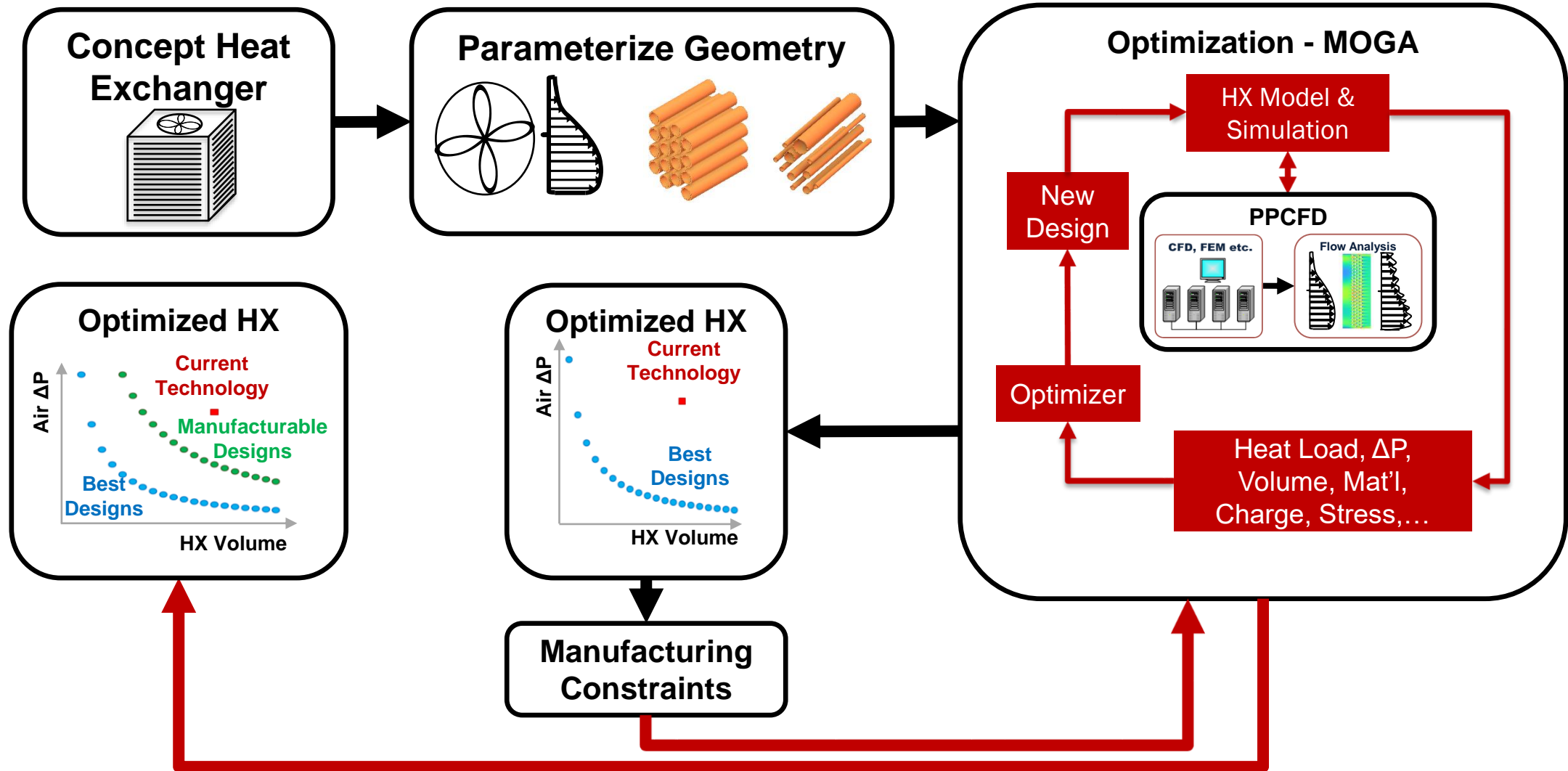


Failure Mode



Adhesives	Lap Shear Adhesion (MPa) at 65°C	Lap Shear Adhesion (MPa) at 90°C	Failure Mode
ORNL-A	7	8.5	Adhesive failure
ORNL-B	7.2	7.6	Adhesive failure
ORNL-C	12.8	12.5	Adhesive failure
ORNL-D	N/A	10.13	Adhesive failure
ORNL-E	N/A	9.02	Adhesive failure

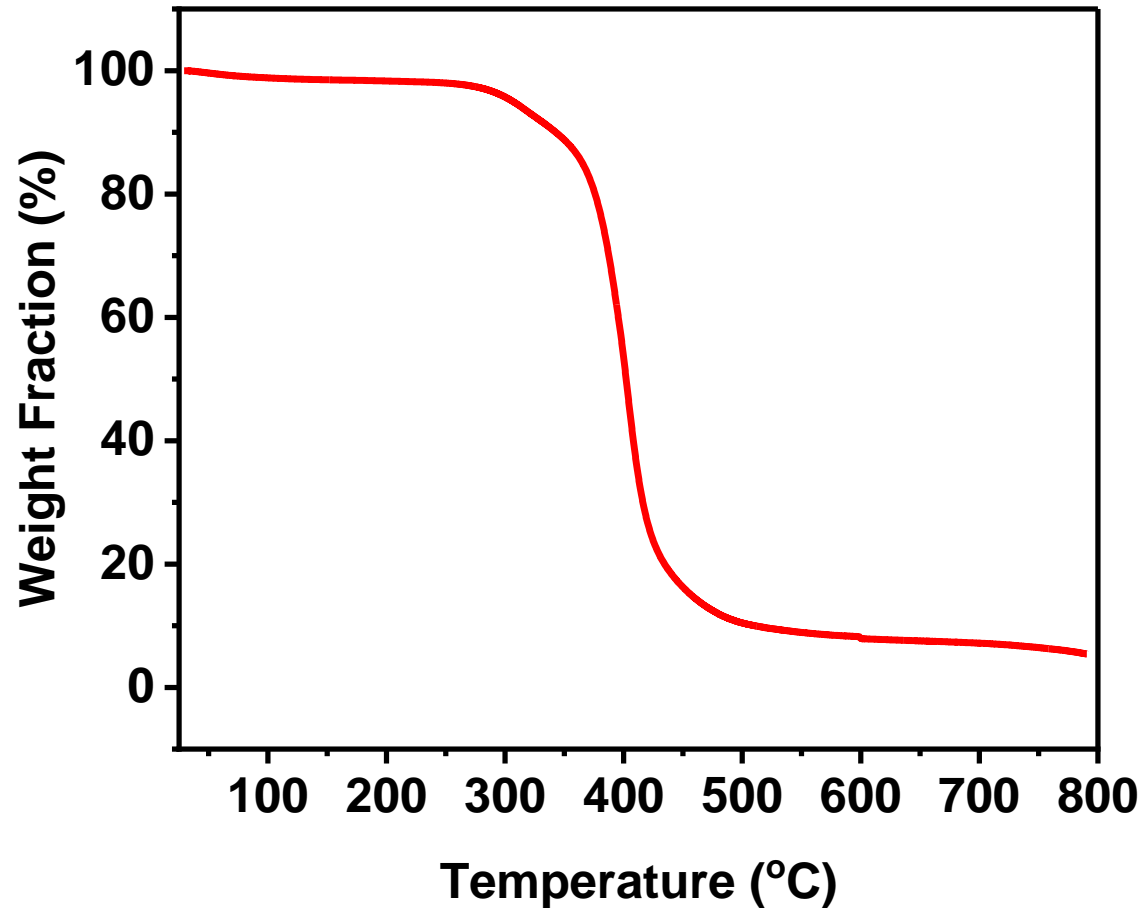
Approach: Design & Optimization Framework



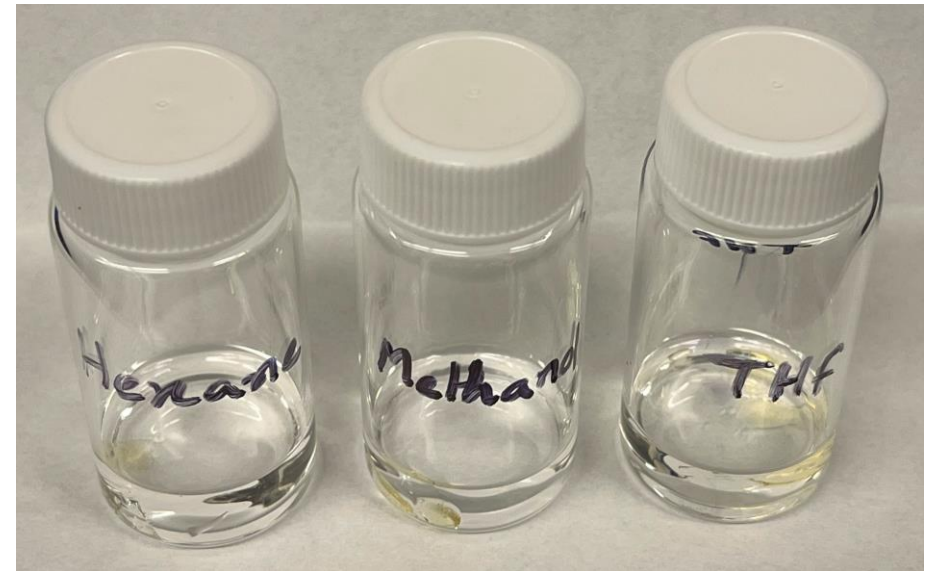
PPCFD = Parallel Parameterized Computational Fluid Dynamics | MOGA = Multi-Objective Genetic Algorithm

Progress: Adhesive Temperature Stability & Solvent Resistance

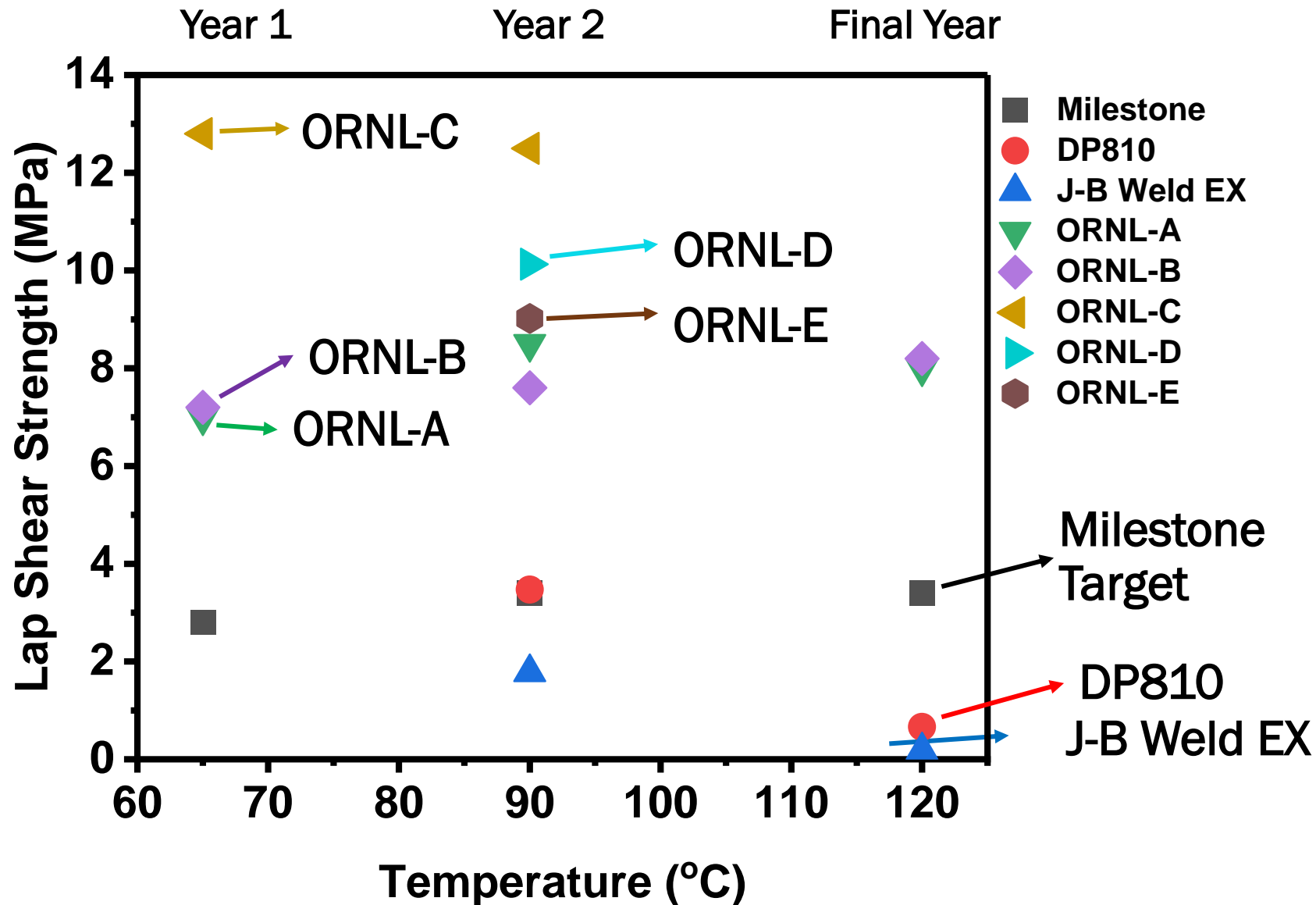
TGA plot indicates very good thermal stability of our adhesive



Excellent solvent resistance

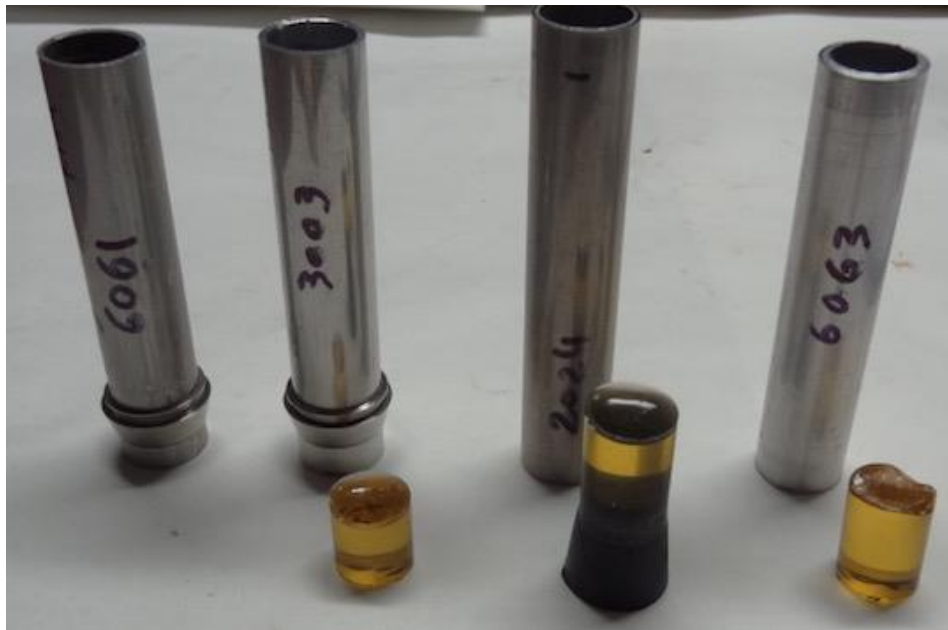


Progress: Current Adhesive Development



Progress: Tube-Adhesive Pressure Testing

- DP8407NS held 3 MPa at 60°C for 30+ minutes (M2.4)
- ORNL-A epoxy held 3.4 MPa at 90°C for 30+ minutes (M3.2) in a 3/8" OD tube
- Narrow bonding area improves adhesion performance



Aluminum Alloy Testing



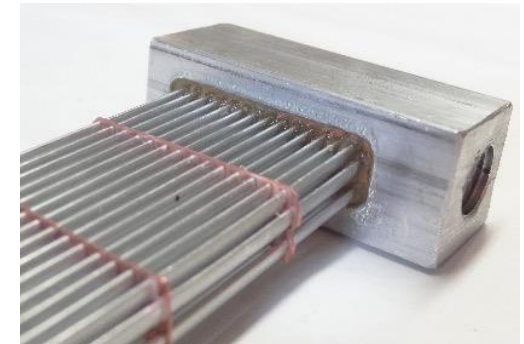
ORNL-A Test



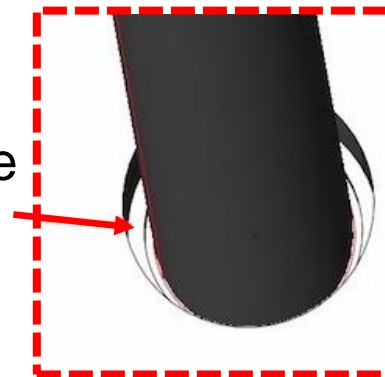
DP8407NS Test

Progress: Heat Exchanger Fabrication

- **Initial Approach**
 - All adhesive header
- **Manifold Method**
 - Reduced cost and adhesive consumption
 - Poor adhesive penetration → leakage
- **Block Header Design**
 - 1.5 mm groove for adhesive application

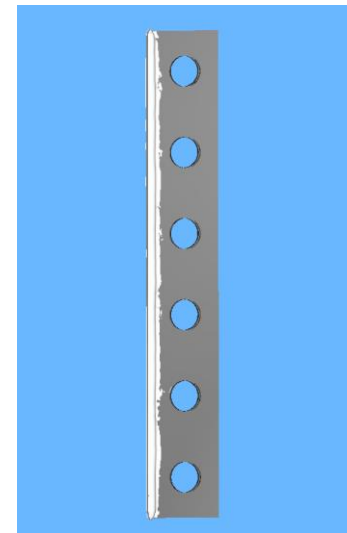
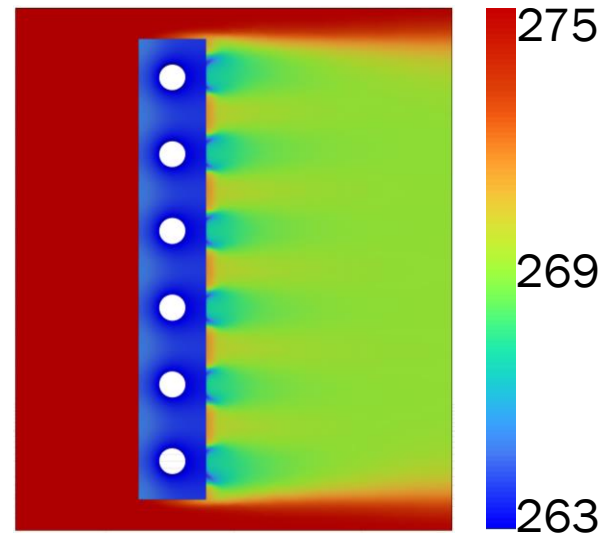
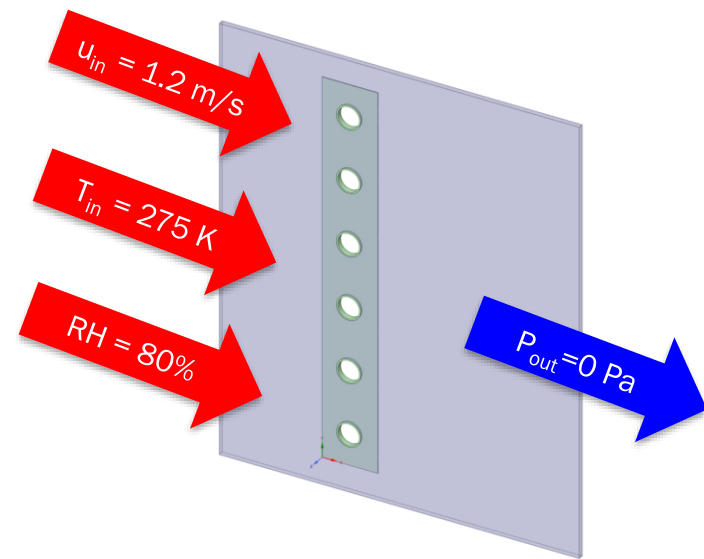


Adhesive groove



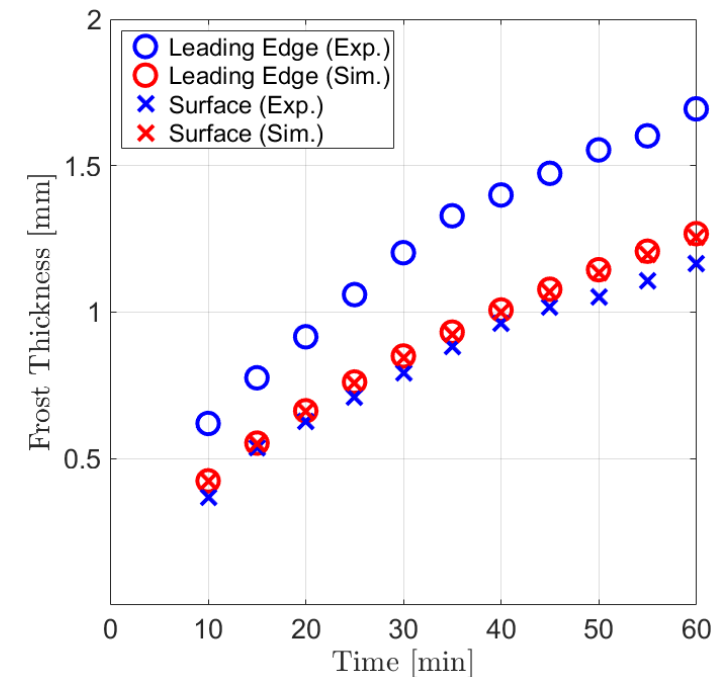
Progress: Frost Accumulation Modeling

- Multiphysics frost accumulation simulations validated with literature data
- Model development challenges
 - Fin conduction (ice accretion model cannot simulate fin conduction)
 - Ice/frost thermophysical properties cause solver stability issues



Assumptions
Constant ice density
Frosting period: 3600s

Settings
Mesh: ~800,000 elements
dt = 0.1s



Future Work

- **Design and Analysis**
 - Finalize frost accumulation analysis
 - Increase scope of packaging considerations in flow prediction
 - VGHX design with improved frost resilience (>10% operational time)
- **Fabrication**
 - Testing and evaluation of block header design
 - Develop additional manufacturing methods
 - HX prototyping (~3 kW lab-scale & ~5-10 kW field-scale)
- **Testing**
 - Continued adhesive testing with tube-pressure test rig
 - Proof-of-concept HX testing & validation
 - Lab-scale: in-house & industry partners
 - Field-scale: industry partners

Thank You

Performing Organizations: University of Maryland, Heat Transfer Technologies, LLC., Oak Ridge National Laboratory

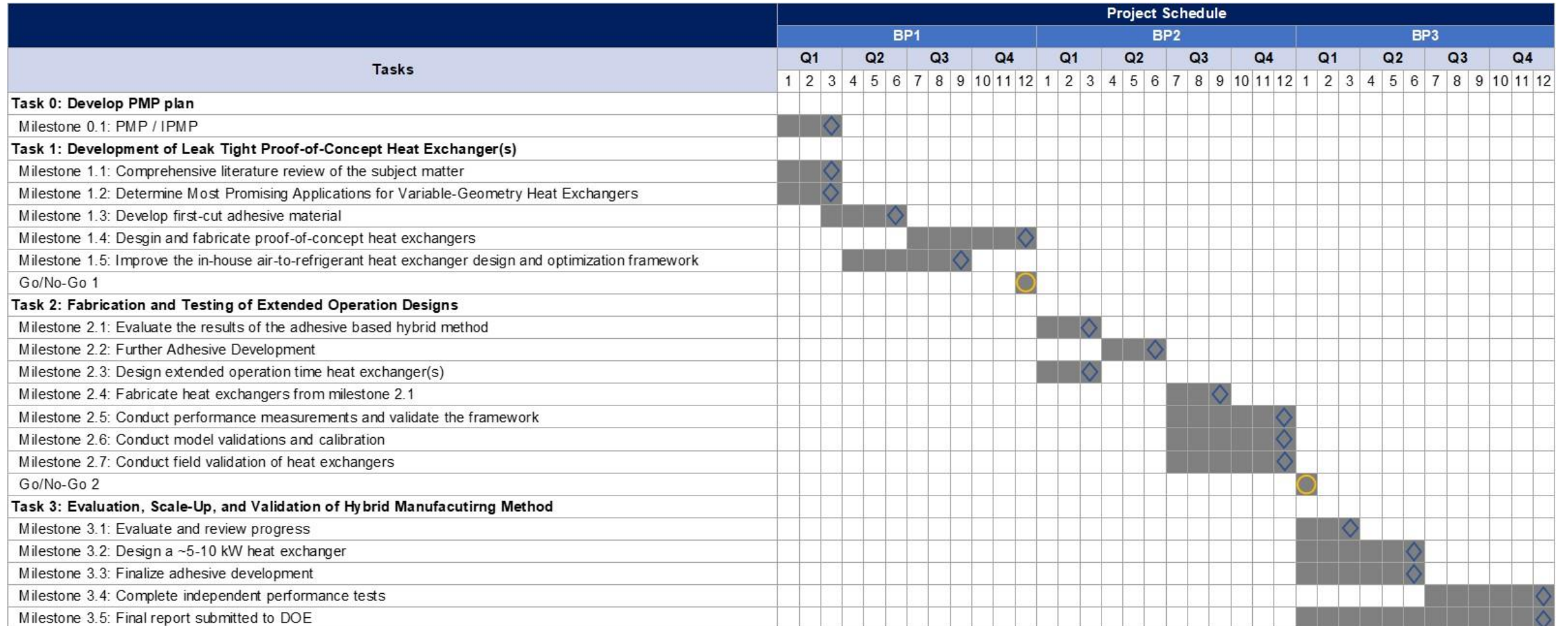
Prof. Reinhard Radermacher, *Dr. Vikrant Aute*

vikrant@umd.edu

DE-EE0009677

REFERENCE SLIDES

Project Execution



◆ Milestone ○ Go/No-Go

Team

- **University of Maryland (Prime recipient)**
 - Component modeling/design, data analysis, project management
- **Heat Transfer Technologies, LLC (Sub-recipient)**
 - Heat exchanger design, assembly, technical advisor
- **Oak Ridge National Laboratory (Sub-recipient)**
 - Adhesive development, laboratory testing, technical advisor
- **Industry Partners**
 - 3M
 - Carrier
 - Goodman / Daikin Comfort Technologies
 - Honeywell
 - Small Tube Products